

NOTES (UNLESS OTHERWISE SPECIFIED):

1. THIS DRAWING SPECIFIES THE REQUIREMENTS FOR A PRINTED WIRING BOARD IN ACCORDANCE WITH SPECIFICATION IPC-6012 CLASS 2 (LATEST REVISION).
2. THE PWB MUST BE LEAD FREE ASSEMBLY PROCESS COMPATIBLE AND MUST BE ABLE TO HANDLE A MINIMUM OF 5 CYCLES AT 240 DEGREES CELSIUS FOR 10 SECONDS.
3. BASE MATERIAL - LAMINATE AND PREPREG SHALL MEET IPC-4101D-26, 83 or 98
T_g - MUST BE GREATER THAN OR EQUAL TO 150 DEGREES CELSIUS.
T_d - MUST BE GREATER THAN OR EQUAL TO 330 DEGREES CELSIUS.
4. COPPER FOIL WEIGHT - SEE STACKUP DETAIL 'A'
5. CHARACTERISTIC IMPEDANCE - NONE
6. MINIMUM CONDUCTIVE WIDTH/SPACING TO BE .008"/.007"
7. PLATING FINISH: A. BOTH SIDES ENIG; TO MEET THE REQUIREMENTS OF IPC-4552 (LATEST REVISION).

ALL THROUGH HOLE VIAS MAY BE PLATED SHUT.

9. SOLDERMASK - TO MEET THE REQUIREMENTS OF IPC-SM-840E (OR LATEST REVISION).
GREEN COLOR, BOTH SIDES.
MODIFICATION OF SOLDERMASK IS NOT ALLOWED WITHOUT WRITTEN PERMISSION FROM NXP.
TYPE: LPI OR EQUIVALENT.
A. LOCATION $\pm .002$ " OF PLATED PADS.
B. DIAMETER OR SIZE $\pm .002$ " OF ORIGINAL DATA

10. SILKSCREEN - WHITE EPOXY OR ACRYLIC INK, BOTH SIDES, NO SILKSCREEN ON ANY EXPOSED COPPER FEATURE.

11. ELECTRICAL TEST - 100% IPCD356.

12. PRINTED WIRING BOARD IS TO BE INDIVIDUALLY BAGGED.

13. DFM CHECK MUST BE RUN ON BOARD DATA BEFORE BUILDING BOARDS, UNLESS PRIOR APPROVAL IS GIVEN IN WRITING BY NXP.

14. TEARDROPS MAY BE ADDED AT THE FAB HOUSE TO ALL SIGNAL LAYERS.

15. TWO SOLDER SAMPLES TO BE PROVIDED.

SUPPLIER MARKINGS - ON SECONDARY SIDE ONLY, WHERE SHOWN.
- MUST BE UL RECOGNIZED AND MUST HAVE AN ID THAT CONFORMS TO UL94V-0

17. THE PWB WILL BE MARKED AS LEAD FREE BY USE OF AN INK STAMP (Pb)

18. THE PWB WILL BE MARKED AS LEAD FREE PROCESS COMPATIBLE BY USE OF AN INK STAMP (260°C)

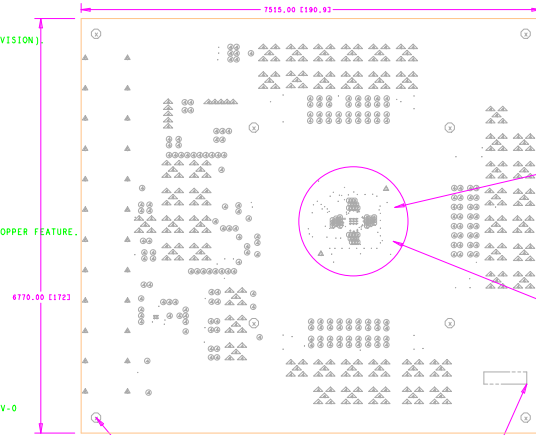
ALL PLATED AND NON-PLATED THROUGH HOLES ARE TO BE DRILLED AT PRIMARY DRILL STEP.
ALL HOLE LOCATION TOLERANCES ARE TO BE $\pm .002$ " IN REFERENCE TO THE PRIMARY DATUM UNLESS OTHERWISE SPECIFIED.

20. FINISHED PCB MUST BE PANELIZED FOR ASSEMBLY ACCORDING TO CONTRACT MANUFACTURERS REQUIREMENTS. THE ADDITION OF RAILS AND .125" NON-PLATED TOOLING HOLES ARE AT THE DISCRETION OF CONTRACT MANUFACTURER. PANELIZATION MUST BE APPROVED BY CONTRACT MANUFACTURER.

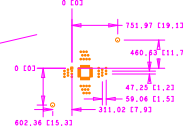
21. THE MANUFACTURE HAS THE OPTION TO ADD COPPER THIEVING ON OUTER AND INNER LAYERS. KEEP A MINIMUM DISTANCE OF .100" FROM ANY BOARD FEATURES.

THIS BOARD USES VIA-IN-PAD: SEE FAB_VIAFILL.ART

- A. ALL VIAS USING X-1 DRILL SIZES ARE TO BE FILLED WITH NON-CONDUCTIVE VIA FILL. LACKWARTER-PETERS PP2795 OR EQUIVALENT AND MADE PLANAR TO THE PADS.
- B. OVERPLATE THE FILLED VIA AND APPLY FINISH METAL TREATMENT.
- C. DIMPLE OR PROTRUSION ON VIA-IN-PADS MUST BE NO GREATER THAN .001".

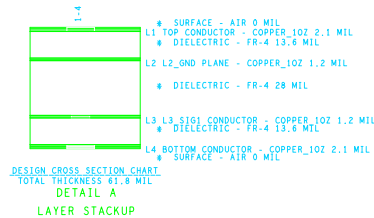


DETAIL C



U1 PIN 1
SECONDARY DATUM
SEE DETAIL C

| DRILL CHART: TOP to BOTTOM | | | | |
|----------------------------|---------------|------------------|------------|-----|
| ALL UNITS ARE IN MILS | | | | |
| FIGURE | FINISHED SIZE | TOLERANCE, DRILL | PLATED | QTY |
| + | 8.0 | +0.0/-8.0 | PLATED | 20 |
| # | 8.1 | +0.0/-8.1 | PLATED | 13 |
| ◇ | 10.0 | +0.0/-10.0 | PLATED | 105 |
| ⊙ | 28.0 | +4.0/-0.0 | PLATED | 40 |
| ⊖ | 40.0 | +3.0/-3.0 | PLATED | 199 |
| ⊕ | 47.0 | +3.0/-3.0 | PLATED | 250 |
| △ | 63.0 | +3.0/-3.0 | PLATED | 24 |
| ▲ | 83.0 | +4.0/-0.0 | NON-PLATED | 2 |
| ⊙ | 138.0 | +2.0/-2.0 | NON-PLATED | 8 |



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| PART NO. 170-30108 | | NXP SEMICONDUCTORS | |
| THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO NXP AND SHALL NOT BE USED FOR ENGINEERING DESIGN, PROCUREMENT OR MANUFACTURE IN WHOLE OR IN PART WITHOUT THE CONSENT OF NXP. | | 6501 WILLIAM CANNON DRIVE WEST AUSTIN, TEXAS 78735 USA | |
| TITLE: PRINTED WIRING BOARD OMPCA9957LEDEV | | REV A | |
| DRAWN STACY CUI 01-22-19 | | SIZE LAY-39109 | |
| CHECKED PETER NAEHRIG 01-22-19 | | ENG. NO. FAB-39109 | |
| DESIGN ENGINEER JUN QIAO 01-22-19 | | SCALE DO NOT SCALE DRAWING | |
| UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: X.XX .01 X.XX .005 ANGLES .0-90° BRO ALL MACHINED SURFACES BREAK ALL SHARP EDGES AND CORNERS REMOVE BURRS UNLESS INDICATED, DIM. NOT TO SCALE. THIRD ANGLE ORTHOGRAPHIC PROJECTION IS USED. | | SHEET OF | |